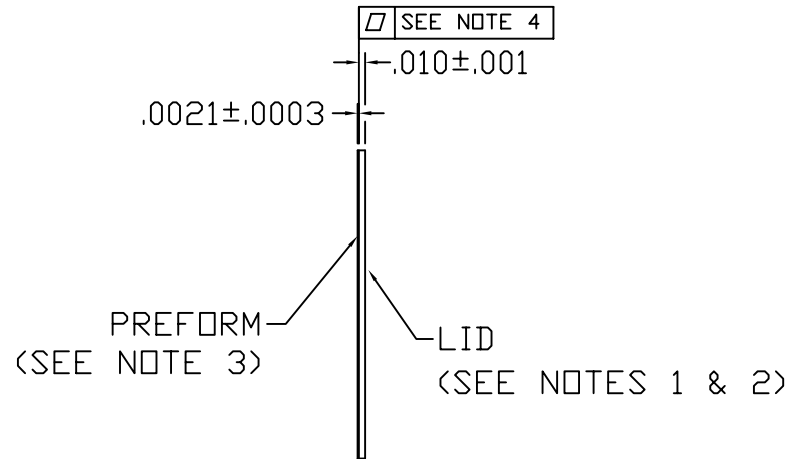
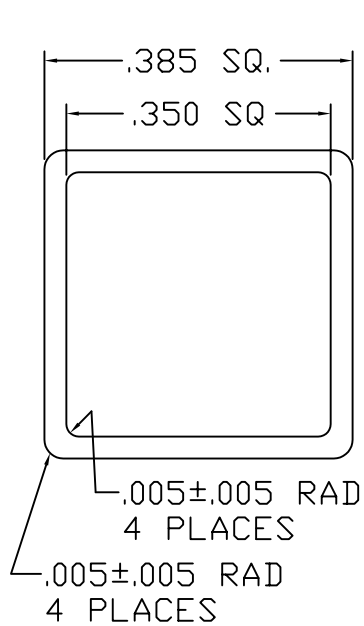


# SSM P/N CL-38504



**NOTES**

1. MAT'L : KOVAR OR ALLOY 42
2. PLATING : 1st LAYER 50/350 MICROINCHES NI  
               2nd LAYER Au  
               3rd LAYER 50/350 MICROINCHES NI  
               4th LAYER 25 MICROINCHES MINIMUM Au

NOTES : TOTAL NICKEL LAYERS SHALL NOT EXCEED 450 MICROINCHES AND THE SUM OF BOTH GOLD LAYERS SHALL BE 50 MICROINCHES MINIMUM.

3. PREFORM - 80% ±1% Au  
               20% Sn
4. FLATNESS : ONE MIL (.001) MAXIMUM PER 1/2" T.I.R
5. TOLERANCES TO BE (XXX) 3 PLACES ±.003 UNLESS OTHERWISE NOTED

**CONTROLLED 4-10-03**

	DESCRIPTION HI REL COMBO LID	
	PART NAME CL-38504	
Spectrum Semiconductor Materials, Inc. 2027 O'Toole Ave San Jose, CA 95131 PH: (408) 435-5555 Fx: (408)435-8226	MFG WILLIAMS ADVANCED MATERIALS	
	PART No. W711H	

